CLAIMS

What is claimed is:

- 1. An apparatus comprising: a plurality of devices formed on a substrate; and a scribe line area separating each of the plurality of devices; and a masking material overlying a portion of the scribe line area.
- 2. The apparatus of claim 1, wherein the masking material is transparent.
- 3. The apparatus of claim 1, wherein the masking material comprises an acrylate moiety.
- 4. The apparatus of claim 1, wherein the masking material has a thickness similar to the thickness of a device portion.
- 5. The apparatus of claim 1, wherein the plurality of devices comprise as one material layer a material comprising one of a colorant.
- The apparatus of claim 5, wherein the colorant comprises a pigment. 6.
- 7. The apparatus of claim 1, wherein the plurality of devices each comprise a sensor portion.
- 8. The apparatus of claim 1, wherein the masking material overlies the entire portion of the scribe line area adjacent the plurality of devices.
- 9. The apparatus of claim 6, wherein the masking material comprises a plurality of discrete structures occupying less than the entire portion of the scribe line area adjacent the plurality of devices.
- 10. A semiconductor wafer comprising: a plurality of devices formed on the wafer, each integrated circuit Express Mail No. EL651846034US

mapped on the surface of a wafer adjacent a scribe line area; and a masking material overlying a portion of the scribe line area.

- 11. The semiconductor wafer of claim 10, wherein the masking material is transparent.
- 12. The semiconductor wafer of claim 10, wherein the masking material has a thickness similar to the thickness of a device portion.
- 13. The semiconductor wafer of claim 4, wherein the plurality of integrated circuits comprise as one material layer, a material comprising one of a colorant.
- 14. The semiconductor wafer of claim 13, wherein the colorant comprises a pigment.
- 15. The semiconductor wafer of claim 10, wherein the plurality of devices comprise a sensor portion.
- 16. The semiconductor wafer of claim 10, wherein the masking material overlies the entire portion of the scribe line area adjacent the plurality of devices.
- 17. The semiconductor wafer of claim 10, wherein the masking material comprises a plurality of discrete structures occupying less than the entire portion of the scribe line area adjacent the plurality of devices.